PMP30284 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C9, C11, C12	4	1uF	GRM188R61C105KA93D	MuRata	CAP, CERM, 1 μF, 16 V,+/- 10%, X5R, 0603	0603
C2 C3	1	0.01uF	GRM188R71E103KA01D	MuRata		0603
	1	180uF	16SVP180M	Panasonic	CAP, Aluminum Polymer, 180 µF, 16 V,+/- 20%, 0.02 ohm	8x10 SMD
C4, C5	2	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22 µF, 25 V,+/- 10%, X7R, 1210	1210
C6	1	470pF	GRM188R71H471KA01D	MuRata	CAP, CERM, 470 pF, 50 V,+/- 10%, X7R, 0603	0603
C7, C8, C14	3	100uF	GRM32ER60J107ME20L	MuRata	CAP, CERM, 100 μF, 6.3 V,+/- 20%, X5R, 1210	1210
C10	1	0.068uF	GRM188R71C683KA01D	MuRata	CAP, CERM, 0.068 µF, 16 V,+/- 10%, X7R, 0603	0603
C13	1	6800pF	GRM188R71E682KA01D	MuRata	CAP, CERM, 6800 pF, 25 V,+/- 10%, X7R, 0603	0603
D1	1	40V	B340A-13-F	Diodes Inc.	Diode, Schottky, 40 V, 3 A, SMA	SMA
D2	1	30V	BAT54-7-F	Diodes Inc.	Diode, Schottky, 30 V, 0.2 A, SOT-23	SOT-23
D3	1	3.6V	MMSZ5227B-7-F	Diodes Inc.	Diode, Zener, 3.6 V, 500 mW, SOD-123	SOD-123
J1, J2	2		ED555/2DS	On-Shore Technology	Terminal Block, 3.5mm Pitch, 2x1, TH	7.0x8.2x6.5mm
J3, J4	2		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin, THT	Header, 3 PIN, 100mil, Tin
L1	1	10uH	MSD1260-103MLB	Coilcraft	Coupled inductor, 10 µH, 3.7 A, 0.06 ohm, SMD	MSD1260
Q1	1	-20V	CSD25404Q3	Texas Instruments	MOSFET, P-CH, -20 V, -60 A, DQG0008A (VSON-CLIP-8)	DQG0008A
Q2	1	25V	CSD16340Q3	Texas Instruments	MOSFET, N-CH, 25 V, 60 A, DQG0008A (VSON-CLIP-8)	DQG0008A
R1	1	0.05	LVK12R050FER	Ohmite	RES, 0.05, 1%, 0.5 W, 1206 sense	1206 sense
R2, R4, R7	3	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.1 W, 0603	0603
R3	1	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0 k, 1%, 0.1 W, 0603	0603
R6	1	124k	CRCW0603124KFKEA	Vishay-Dale	RES, 124 k, 1%, 0.1 W, 0603	0603
R8	1	33.2k	CRCW060333K2FKEA	Vishay-Dale	RES, 33.2 k, 1%, 0.1 W, 0603	0603
R9	1	49.9	CRCW060349R9FKEA			0603
R10, R11	2	10.0	CRCW060310R0FKEA	Vishay-Dale	RES, 10.0, 1%, 0.1 W, 0603	0603
TP1, TP3, TP10	3		5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP2, TP4, TP6,	4		5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
TP9						
TP5	1		5004	Keystone	Test Point, Miniature, Yellow, TH	Yellow Miniature Testpoint
TP7, TP8	2		5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
U1	1		TLV6001UIDBVR	Texas Instruments	1-MHz, Low-Power Operational Amplifier for Cost-Sensitive Systems, DBV0005A (SOT-23-5)	DBV0005A
U2	1		TPS43000PW	Texas Instruments	Multi-Topology (buck, boost, sepic) High Frequency DC/DC Controller, PW0016A (TSSOP-16)	PW0016A

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